

ABSTRACT

Methods for inspecting a wafer are provided. One method includes directing light to a center portion and an edge portion of a wafer in a single scan. The method also includes
5 detecting light scattered from the center portion using a first detection channel and detecting light scattered from the edge portion using a second detection channel. Another method for inspecting an edge portion of a wafer includes scanning the edge portion of the wafer with light. The method also includes separately detecting different portions of light scattered from the edge portion. In addition, the method includes separating light scattered from edge features in the
10 edge portion from other light scattered from the edge portion. The method further includes detecting defects in the edge portion of the wafer using the other scattered light.